SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

TPS3820, TPS3823, TPS3828...DBV PACKAGE

FEATURES

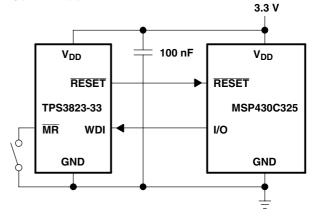
- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Using Human Body Model (C = 100 pF, R = 1500 Ω)
- Power-On Reset Generator With Fixed Delay Time of 200 ms (TPS3823/4/5/8) or 25 ms (TPS3820)
- Manual Reset Input (TPS3820/3/5/8)
- Reset Output Available in Active-Low (TPS3820/3/4/5), Active-High (TPS3824) and Open-Drain (TPS3828)
- Supply Voltage Supervision Range 2.5 V, 3 V, 3.3 V, 5 V
- Watchdog Timer (TPS3820/3/4/8)
- Supply Current of 15 μA (Typ)
- SOT23-5 Package

APPLICATIONS

- Applications Using Automotive DSPs, Microcontrollers, or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems
- Battery-Powered Equipment
- Intelligent Instruments
- Wireless Communications Systems

(TOP VIEW) RESET V_{DD} GND 2 WDI MR 4 TPS3824 . . . DBV PACKAGE (TOP VIEW) $\neg v_{DD}$ RESET GND WDI RESET **TPS3825...DBV PACKAGE** (TOP VIEW) RESET 5 V_{DD} GND 4 MR RESET

typical application



description

The TPS382x family of supervisors provides circuit initialization and timing supervision, primarily for DSP and processor-based systems.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



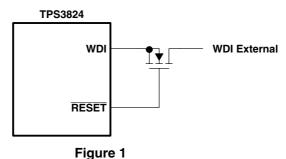
SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

description (continued)

During power-on, RESET is asserted when supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps RESET active as long as V_{DD} remains below the threshold voltage V_{IT-} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, t_d , starts after V_{DD} has risen above the threshold voltage V_{IT-} . When the supply voltage drops below the threshold voltage V_{IT-} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage V_{IT-} set by an internal voltage divider.

The TPS3820/3/5/8 devices incorporate a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. The TPS3824/5 devices include a high-level output RESET. TPS3820/3/4/8 have a watchdog timer that is periodically triggered by a positive or negative transition at WDI. When the supervising system fails to retrigger the watchdog circuit within the time-out interval, t_{tout} , $\overline{\text{RESET}}$ becomes active for the time period t_d . This event also reinitializes the watchdog timer. Leaving WDI unconnected disables the watchdog.

In applications where the input to the WDI pin may be active (transitioning high and low) when the TPS3820/3/4/8 is asserting RESET, the TPS3820/3/4/8 does not return to a non-reset state when the input voltage is above Vt. If the application requires that input to WDI is active when RESET is asserted, WDI must be decoupled from the active signal. This can be accomplished by using an N-channel FET in series with the WDI pin, with the gate of the FET connected to the RESET output as shown in Figure 1.



The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 5-pin SOT23-5 package. The TPS382x-xxQ devices are characterized for operation over a temperature range of –40°C to 125°C, and are qualified in accordance with AEC-Q100 stress test qualification for integrated circuits.

SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

PACKAGE INFORMATION^{†‡}

DEVICE NAME	THRESHOLD VOLTAGE	MARKING
TPS3820-33QDBVRQ1§	2.93 V	PDEQ
TPS3820-50QDBVRQ1§	4.55 V	PDDQ
TPS3823-25QDBVRQ1§	2.25 V	PAPQ
TPS3823-30QDBVRQ1§	2.63 V	PAQQ
TPS3823-33QDBVRQ1§	2.93 V	PARQ
TPS3823-50QDBVRQ1§	4.55 V	PASQ
TPS3824-25QDBVRQ1§	2.25 V	PATQ
TPS3824-30QDBVRQ1§	2.63 V	PAUQ
TPS3824-33QDBVRQ1§	2.93 V	PAVQ
TPS3824-50QDBVRQ1§	4.55 V	PAWQ
TPS3825-33QDBVRQ1§	2.93 V	PDGQ
TPS3825-50QDBVRQ1§	4.55 V	PDFQ
TPS3828-33QDBVRQ1§	2.93 V	PDIQ
TPS3828-50QDBVRQ1§	4.55 V	PDHQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION/TRUTH TABLE

INP	UTS	OUTPUTS			
MR‡	$V_{DD}>V_{IT}$	RESET	RESET§		
L	0	L	Н		
L	1	L	Н		
Н	0	L	Н		
Н	1	Н	L		

[‡] TPS3820/3/5/8

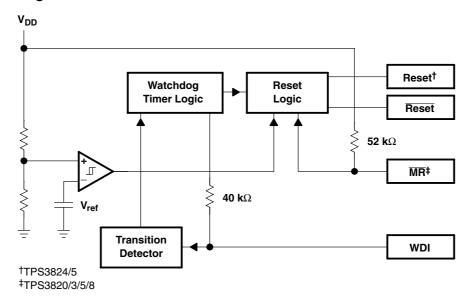
[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

[§] The DBVR package indicates tape and reel of 3000 parts.

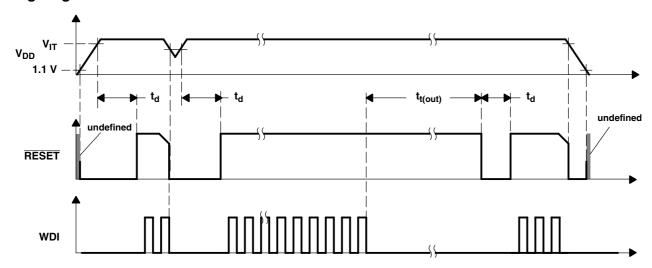
[§] TPS3824/5

SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

functional block diagram



timing diagram



SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD} (see Note 1)	6 V
RESET, RESET, MR, WDI (see Note 1)	
Maximum low output current, I _{OL}	5 mA
Maximum high output current, I _{OH}	–5 mA
Input clamp current range, $I_{ K }(V_1 < 0 \text{ or } V_1 > V_{DD})$	±10 mA
Output clamp current range, I _{OK} (V _O < 0 or V _O > V _{DD})	±10 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
Soldering temperature	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	OPERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW	87 mW

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V _{DD}		1.1	5.5	V
Input voltage, V _I		0	$V_{DD} + 0.3$	V
High-level input voltage at $\overline{\text{MR}}$ and WDI, V_{IH}	0.	$.7 \times V_{DD}$		V
Low-level input voltage, V _{IL}			$0.3 \times V_{DD}$	V
Input transition rise and fall rate at $\overline{\text{MR}}$ or WDI, $\Delta t/\Delta V$			100	ns/V
Operating free-air temperature range, T _A		-40	125	°C



SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	<u> </u>		TEST CONDITIONS	MIN	TYP	MAX	UNIT
			TPS382x-25	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -20 \mu\text{A}$				
		RESET	TPS382x-30 TPS382x-33	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -30 \mu\text{A}$	$0.8 \times V_{DD}$			V
			TPS382x-50	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OH} = -120 \mu\text{A}$	V _{DD} – 1.5 V			
V _{OH}	OH High-level output voltage		TPS3824-25 TPS3825-25	$V_{DD} \ge 1.8 \text{ V}, I_{OH} = -100 \ \mu\text{A}$				
			TPS3824-30 TPS3825-30		1			
		RESET	TPS3824-33 TPS3825-33	V _{DD} ≥ 1.8 V, I _{OH} = −150 μA	$0.8 \times V_{DD}$			V
			TPS3824-50 TPS3825-50					
			TPS3824-25 TPS3825-25	$V_{DD} = V_{IT-} + 0.2 V$ $I_{OL} = 1 \text{ mA}$				
		RESET	TPS3824-30 TPS3825-30	V _{DD} = V _{IT} + 0.2 V	1			
			TPS3824-33 TPS3825-33	I _{OL} = 1.2 mA			0.4	V
V _{OL}	Low-level output voltage		TPS3824-50 TPS3825-50	$V_{DD} = V_{IT-} + 0.2 \text{ V}$ $I_{OL} = 3 \text{ mA}$	1			
			TPS382x-25 $V_{DD} = V_{IT} - 0.2 \text{ V}$ $I_{OL} = 1 \text{ mA}$					
		DECET	TPS382x-30	$V_{DD} = V_{IT-} - 0.2 \text{ V}$			0.45	V
		RESET	TPS382x-33	I _{OL} = 1.2 mA			0.45	V
			TPS382x-50	$V_{DD} = V_{IT-} - 0.2 V$ $I_{OL} = 3 \text{ mA}$				
	Power-up reset voltage (see I	Note 2)		$V_{DD} \geq 1.1 \ V, \ I_{OL} = 20 \ \mu A$			0.4	V
,			TPS382x-25		2.21	2.25	2.30	
			TPS382x-30	T _ 0°C to 95°C	2.59	2.63	2.69	٧
			TPS382x-33	T _A = 0°C to 85°C	2.88	2.93	3	V
V	Negative-going input threshol	d	TPS382x-50		4.49	4.55	4.64	
V_{IT-}	voltage (see Note 3)		TPS382x-25		2.19	2.25	2.30	
			TPS382x-30	T ₄ = _40°C to 125°C	2.55	2.63	2.69	V
			TPS382x-33	$T_A = -40^{\circ}$ C to 125°C	2.84	2.93	3	\ \ \
			TPS382x-50		4.44	4.55	4.65	
			TPS382x-25					
V_{hys}	Hysteresis at V _{DD} input		TPS382x-30		30			mV
riiys	v _{hys} hysteresis at v _{DD} input		TPS382x-33					•
			TPS382x-50	antina to SAF naA/		50		

NOTES: 2. The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. $t_{r,\ VDD} \geq 15\ \mu\text{s/V}$



^{3.} To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 µF) should be placed near the supply terminals.

SGLS143B - DECEMBER 2002 - REVISED JUNE 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

	PARAMETER	?		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{IH(AV)}	Average high-level input curr	ent	LAUD!	WDI = V _{DD} , time average (dc = 88%)		120		
I _{IL(AV)}	Average low-level input curre	nt	WDI	WDI = 0.3 V, V _{DD} = 5.5 V time average (dc = 12%)		-15		
			WDI	$WDI = V_{DD}$		140	190	μΑ
I _{IH}	IH High-level input current		MR	$\overline{MR} = V_{DD} \times 0.7,$ $V_{DD} = 5.5 \text{ V}$		-40	-60	
			WDI	WDI = 0.3 V, V _{DD} = 5.5 V		140	190	
I _{IL}	Low-level input current		MR	$\overline{MR} = 0.3 \text{ V}, \ \text{V}_{DD} = 5.5 \text{ V}$		-110	-160	
			TPS382x-25					
	Output short-circuit current	DECET	TPS382x-30	$V_{DD} = V_{IT, max} + 0.2 V,$			-400	
Ios	(see Note 4)	RESET	TPS382x-33	$V_O = 0 V$				μΑ
			TPS382x-50				-800	
I _{DD}	Supply current	WDI and MR unconnected, Outputs unconnected		15	25	μА		
Internal pullup resistor at MR						52		kΩ
Ci	Input capacitance at MR, WD)I		V _I = 0 V to 5.5 V		5		pF
9	input supusitarios at ivii i, vve			1 = 0 1 10 0.0 V				- 1

NOTE 4: The $\overline{\text{RESET}}$ short-circuit current is the maximum pullup current when $\overline{\text{RESET}}$ is driven low by a μP bidirectional reset pin.

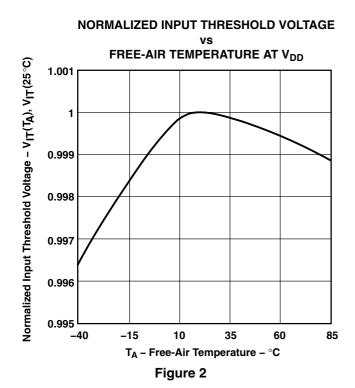
timing requirements at R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

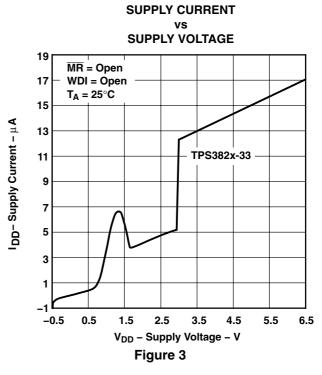
	PARAMET	ER		MIN	MAX	UNIT		
		at V _{DD}	$V_{DD} = V_{IT-} + 0.2 V,$	$V_{DD} = V_{IT} - 0.2 V$		6		μs
$t_{\mathbf{w}}$	Pulse width	at MR	$V_{DD} \ge V_{IT-} + 0.2 \ V,$	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	1		μs
		at WDI	$V_{DD} \ge V_{IT-} + 0.2 \ V,$	$V_{IL} = 0.3 \times V_{DD}$	$V_{IH} = 0.7 \times V_{DD}$	100		ns

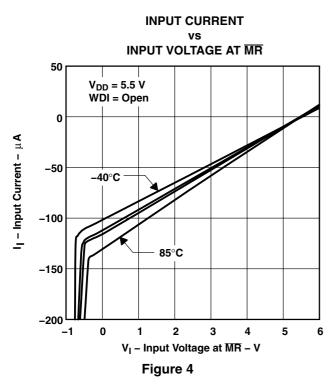
switching characteristics at R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

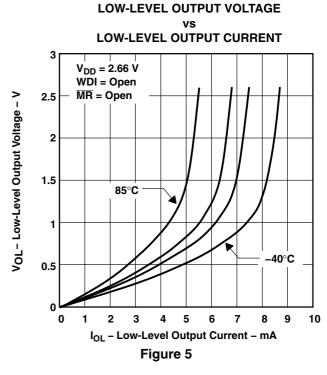
	PARAME	TER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Madalada a Barana	TPS3820	$V_{DD} \ge V_{IT} + 0.2 V$,	112	200	310	ms
t _{tout}	Watchdog time out	TPS3823/4/8	See Timing Diagram	0.9	1.6	2.5	s
t _d Delay time		TPS3820	$V_{DD} \ge V_{IT-} + 0.2 V$,	15	25	37	
		TPS3823/4/5/8	See timing diagram	120	200	300	ms
Propagation (delay) time, ^t PHL high-to-low-level output	$\begin{array}{l} \overline{\text{MR}} \text{ to RESET delay} \\ \text{(TPS3820/3/5/8)} \end{array} \\ \begin{array}{l} V_{DD} \geq V_{IT-} + 0.2 \text{ V}, \\ V_{IL} = 0.3 \text{ x } V_{DD}, \\ V_{IH} = 0.7 \text{ x } V_{DD} \end{array}$				0.1	μs	
	nigh-to-low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$			25	
Propagation (delay) time,		MR to RESET delay (TPS3824/5)	$V_{DD} \ge V_{IT-} + 0.2 \text{ V},$ $V_{IL} = 0.3 \text{ x } V_{DD},$ $V_{IH} = 0.7 \text{ x } V_{DD}$			0.1	μs
	low-to-high-level output	V _{DD} to RESET delay (TPS3824/5)	$V_{IL} = V_{IT} - 0.2 \text{ V},$ $V_{IH} = V_{IT} + 0.2 \text{ V}$			25	

TYPICAL CHARACTERISTICS

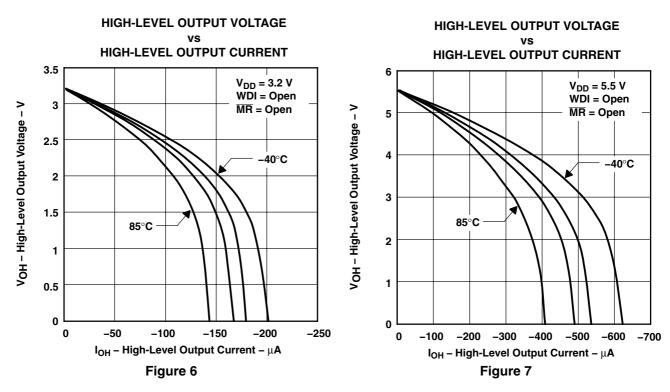




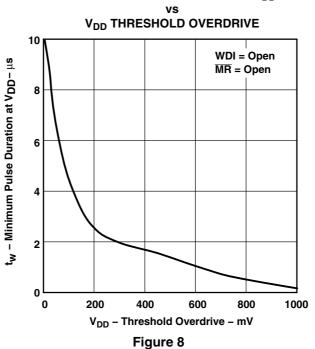




TYPICAL CHARACTERISTICS



MINIMUM PULSE DURATION AT V_{DD}







26-Aug-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
2T25-50QFRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDFQ	Samples
2T28-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDIQ	Samples
2U3820-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDDQ	Samples
2U3823-25QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAPQ	Samples
2U3823-30QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAQQ	Samples
2U3823-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PARQ	Samples
2U3823-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PASQ	Samples
2U3824-25QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PATQ	Samples
2U3824-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAVQ	Samples
2U3824-50QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAWQ	Samples
2U3825-33QDBVRG4Q1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDGQ	Samples
TPS3820-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDEQ	Samples
TPS3820-50DBVRQ1G4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PKG4	Samples
TPS3820-50QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDDQ	Samples
TPS3823-25QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAPQ	Samples
TPS3823-30QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAQQ	Samples
TPS3823-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PARQ	Samples





26-Aug-2013

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3823-50QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PASQ	Samples
TPS3824-25QDBVRQ1	OBSOLETE	SOT-23	DBV	5		TBD	Call TI	Call TI	-40 to 125		
TPS3824-30QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAUQ	Samples
TPS3824-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAVQ	Samples
TPS3824-50QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PAWQ	Samples
TPS3825-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDGQ	Samples
TPS3825-50QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDFQ	Samples
TPS3828-33QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDIQ	Samples
TPS3828-50QDBVRG4Q	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PDHQ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

26-Aug-2013

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS3820-33-Q1, TPS3820-50-Q1, TPS3823-25-Q1, TPS3823-30-Q1, TPS3823-33-Q1, TPS3823-50-Q1, TPS3824-25-Q1, TPS3824-25-Q1, TPS3824-30-Q1, TPS3824-50-Q1, TPS3825-33-Q1, TPS3825-33-Q1, TPS3825-33-Q1, TPS3825-30-Q1, TPS3825-

● Catalog: TPS3820-33, TPS3820-50, TPS3823-25, TPS3823-30, TPS3823-33, TPS3823-50, TPS3824-25, TPS3824-30, TPS3824-33, TPS3824-50, TPS3825-33, TPS3825-33, TPS3828-50

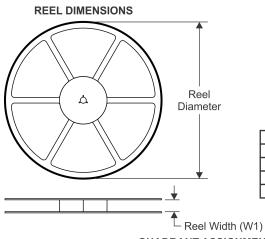
NOTE: Qualified Version Definitions:

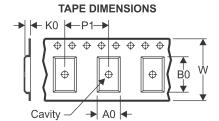
Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 12-Aug-2013

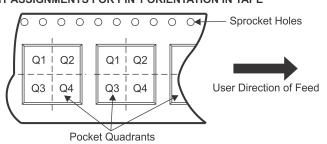
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



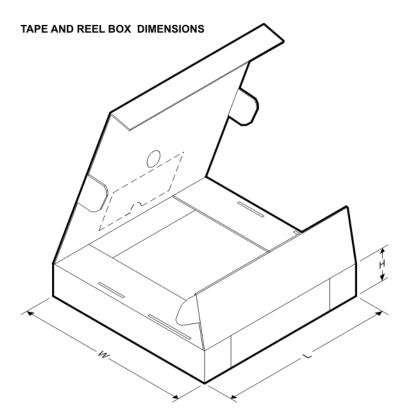
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
2T25-50QFRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2T28-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3820-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-25QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-30QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3823-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-25QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3824-50QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
2U3825-33QDBVRG4Q1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-50DBVRQ1G4	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3820-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-25QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-30QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3823-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

www.ti.com 12-Aug-2013

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3824-30QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3824-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3824-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3825-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3825-50QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3828-33QDBVRQ1	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3828-50QDBVRG4Q	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
2T25-50QFRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2T28-33QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3820-50QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3823-25QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3823-30QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3823-33QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3823-50QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3824-25QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3824-33QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
2U3824-50QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0



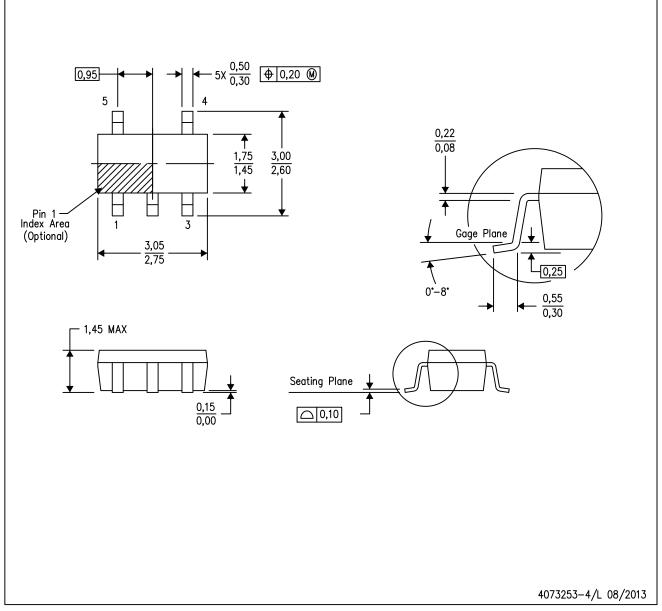
PACKAGE MATERIALS INFORMATION

www.ti.com 12-Aug-2013

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	<u> </u>	, ,			<u> </u>		
2U3825-33QDBVRG4Q1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-50DBVRQ1G4	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3820-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-25QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-30QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3823-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-30QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3824-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3825-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3825-50QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3828-33QDBVRQ1	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3828-50QDBVRG4Q	SOT-23	DBV	5	3000	182.0	182.0	20.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



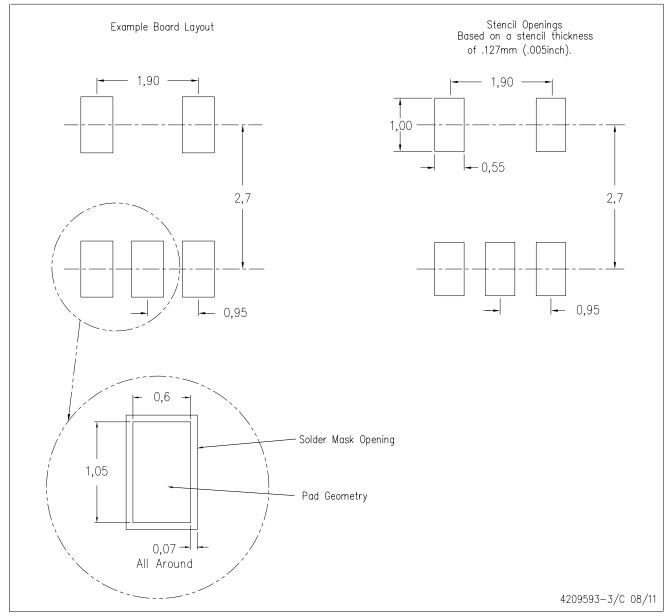
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>